

ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- One red, one green, two blue chips in one package.
- Can produce any color in visible spectrum, including white light.
- RoHS compliant.

T-1 3/4 (5mm) LED LAMP

Part Number: WPF5WAEMBGMBW

High Efficiency Red Blue Green

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Blue source color devices are made with GaN on SiC Light Emitting Diode.

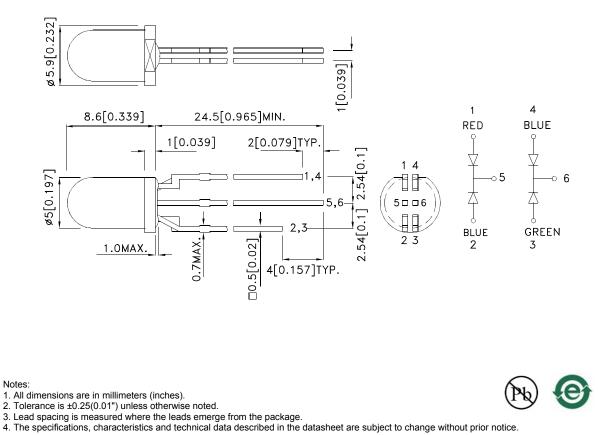
The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



REV NO: V.3 CHECKED: Allen Liu

DATE: JUL/14/2010 DRAWN: C.H.HAN

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Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
WPF5WAEMBGMBW	High Efficiency Red (GaAsP/GaP)		10	30	60°
	Blue (GaN)		7	25	
	Green (GaP)	- WHITE DIFFUSED	7	20	
	Blue (GaN)	7	7	25	

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions			
λpeak	Peak Wavelength	High Efficiency Red Blue Green	627 430 565		nm	IF=20mA			
λD [1]	Dominant Wavelength	High Efficiency Red Blue Green	625 466 568		nm	IF=20mA			
Δλ1/2	Spectral Line Half-width	High Efficiency Red Blue Green	45 60 30		nm	IF=20mA			
С	Capacitance	High Efficiency Red Blue Green	15 100 15		pF	VF=0V;f=1MHz			
VF [2]	Forward Voltage	High Efficiency Red Blue Green	2 3.8 2.2	2.5 4.5 2.5	V	I⊧=20mA			
lr	Reverse Current	High Efficiency Red Blue Green		10 10 10	uA	Vr=5V			

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

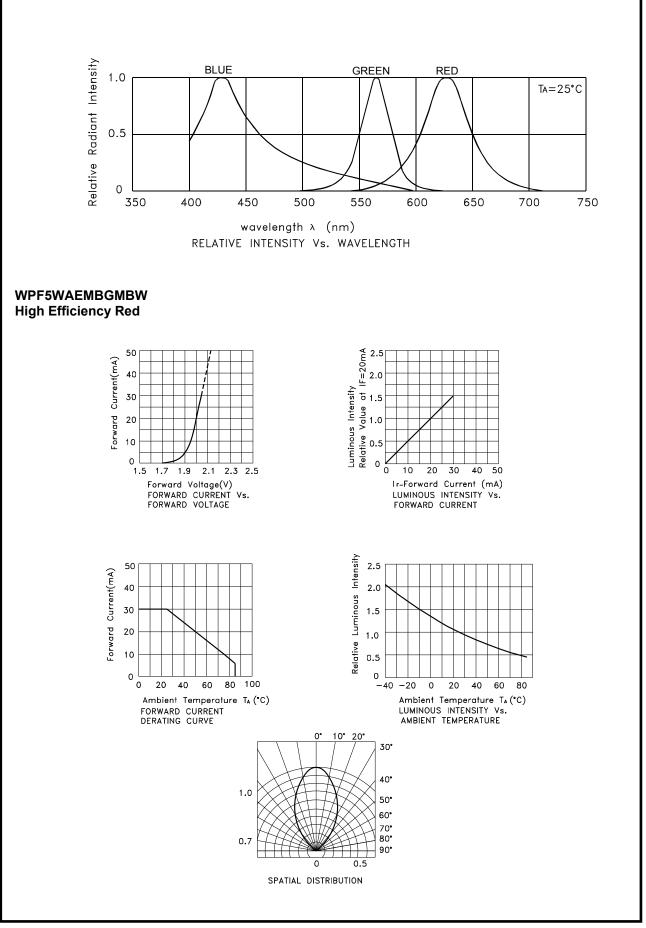
Absolute Maximum Ratings at TA=25°C

High Efficiency Red	Blue	Green	Units		
75	135	62.5	mW		
30	30	25	mA		
160	150	140	mA		
	V				
-40°C To +85°C					
260°C For 3 Seconds					
260°C For 5 Seconds					
	75 30	75 135 30 30 160 150 5 -40°C To +88 260°C For 3 Se	75 135 62.5 30 30 25 160 150 140 5 -40°C To +85°C 260°C For 3 Seconds		

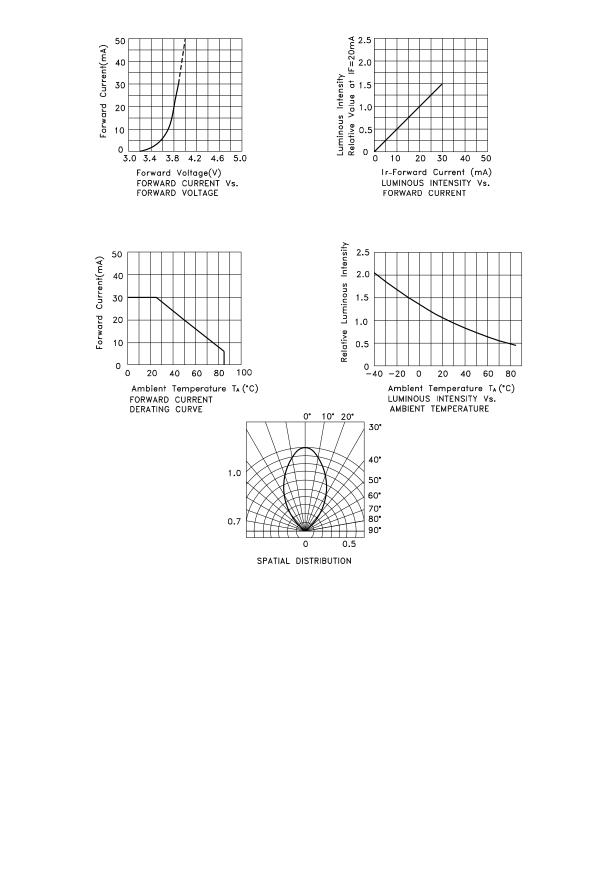
Notes:

1.1/10 Duty Cycle, 0.1ms Pulse Width.
2.2mm below package base.
3.5mm below package base.

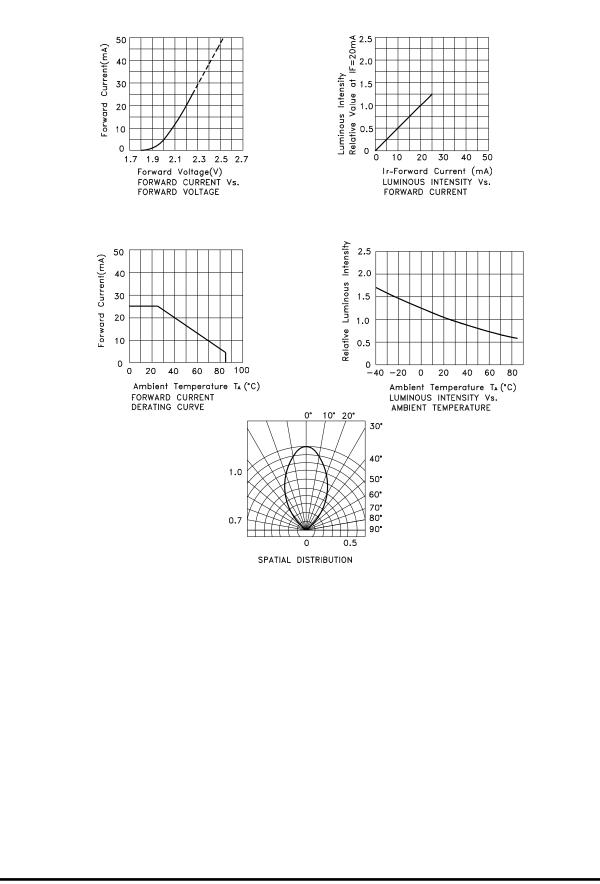
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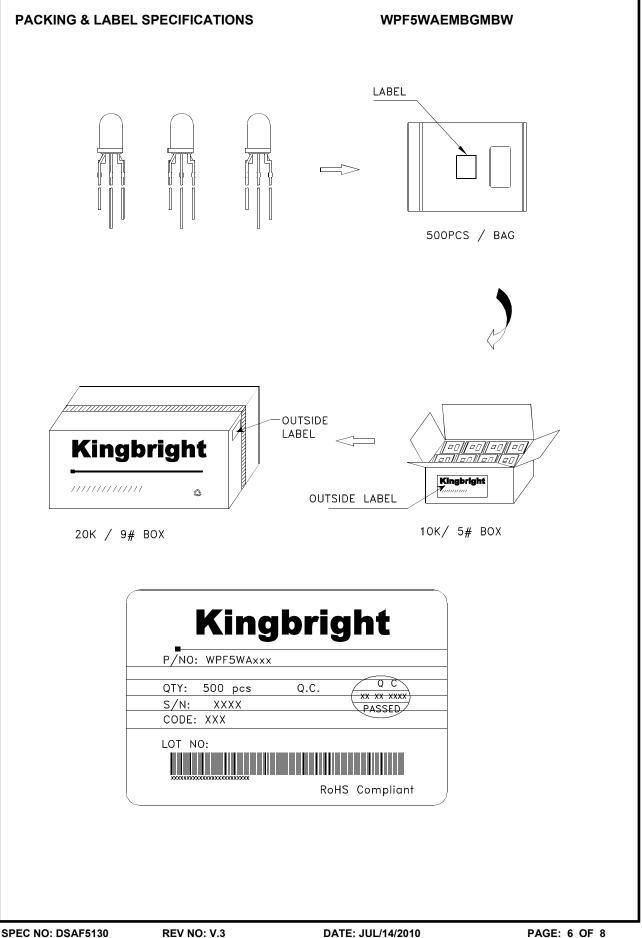


Blue



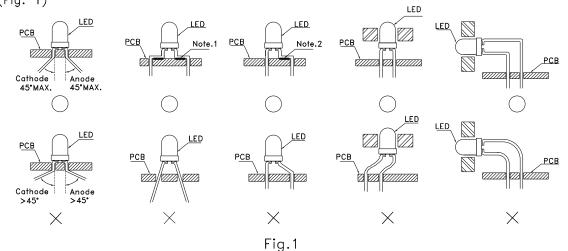
Green





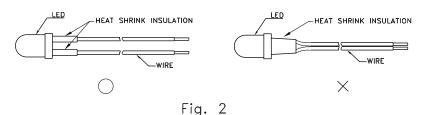
LED MOUNTING METHOD

 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

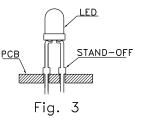


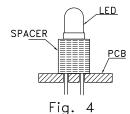
" \bigcirc " Correct mounting method " \times " Incorrect mounting method Note 1-2 : Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig. 2)



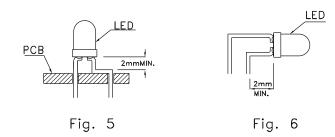
3. Use stand-offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.



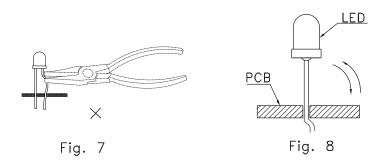


LEAD FORMING PROCEDURES

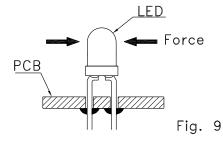
1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



- 2. Lead forming or bending must be performed before soldering, never during or after Soldering.
- 3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
- 4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
- 5. Do not bend the leads more than twice. (Fig. 8)



6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.



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